

SOT1081-2

plastic, extremely thin small outline package; 10 terminals;
0.35 mm pitch; 1.7 mm x 1 mm x 0.5 mm body

13 August 2021

Package information

1 Package summary

Terminal position code	D (double)
Package type descriptive code	XSON10
Package type industry code	XSON10
Package style descriptive code	XSON (extremely thin small outline; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	30-03-2011
Manufacturer package code	SOT1081-2

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	1.6	1.7	1.8	mm
package width	0.9	1	1.1	mm
seated height	-	-	0.5	mm
nominal pitch	-	0.35	-	mm
actual quantity of termination	-	10	-	



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2 Package outline

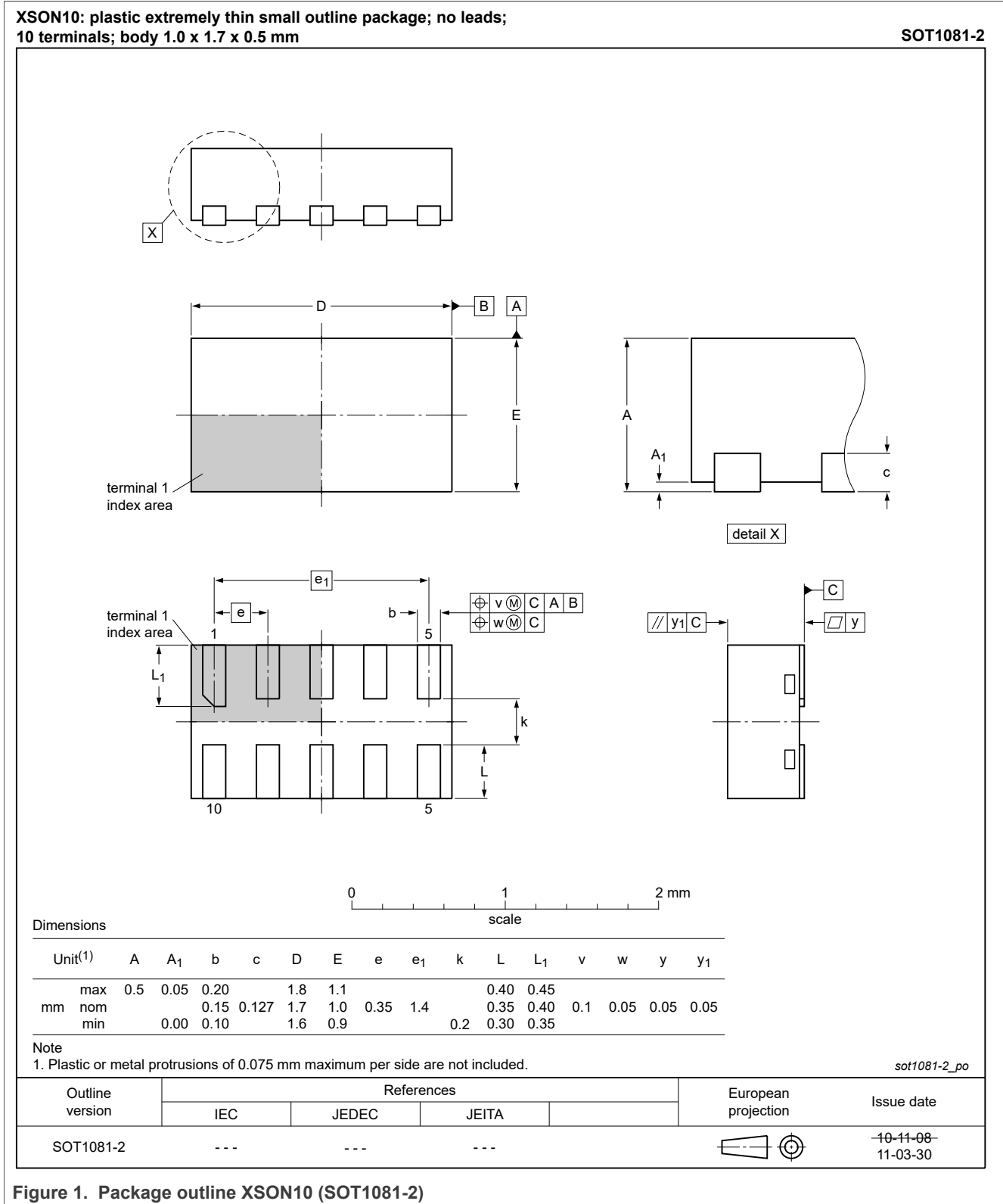


Figure 1. Package outline XSON10 (SOT1081-2)

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body

3 Legal information

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